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10 Plasma: Nature's Way of Manufacturing
by Steven Lowder

20 Considerations for the Deployment of Plasma in HDI Manufacturing
by Lou Fierro & Dr. James D. Getty

26 Emerging Plasma Technology
by Tim Von Werne

42 Conversations with... Imagineering
by Marcy LaRont

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Having Lead-Free Soldering Issues?

by John Coonrod
ROGERS CORP.

The laminates used in the PCB industry have advanced over the years. However, unless you are in tune with the laminate industry or have a PCB issue which requires your attention, you may be unaware of recent developments. The past few years have placed more attention on the PCB materials regarding lead-free soldering, very high layer count, environmental issues and more electrical concerns.

The laminate industry recently brought several different products to the market to address these issues, but as with all things in the technical community, there are always trade-offs. When you consider the different attributes required of a PCB laminate, there is no perfect laminate. Each laminate has its own list of pros and cons, and users should choose the product that best fits their needs.

The lead-free soldering issue has several material property concerns, such as the glass transition (T_g), CTE (coefficient of thermal expansion) and T_d (decomposition temperature). Knowing these numbers for a laminate is a good reference, but it doesn't tell you the whole story. A laminate with a higher T_g is generally good, but the actual TMA curve should be evaluated to understand what happens, thermally, on both sides of

The laminate industry recently brought several products to the market to address issues such as lead-free soldering, high layer count, environmental concerns and more. As with all things in the technical community, there are always trade offs. When you consider the different attributes required, there is no perfect PCB laminate.

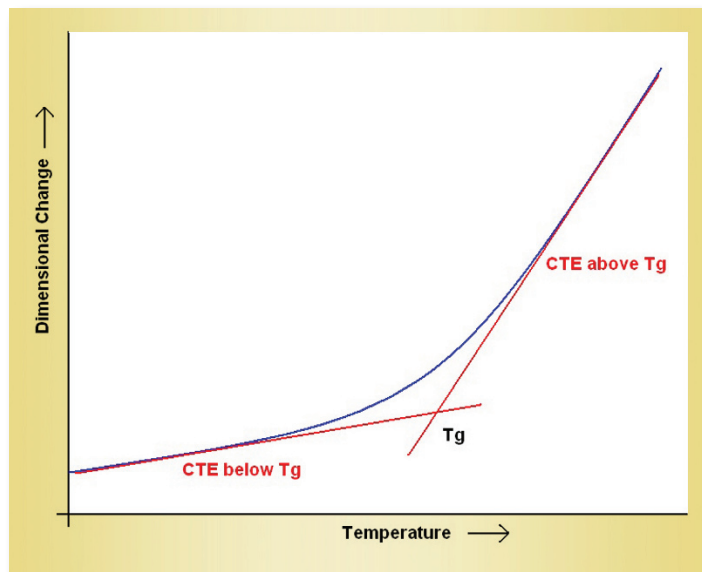


Figure 1. Simplified drawing of a TMA curve showing T_g and CTE performance.

the T_g . A material with a T_g of 180°C is considered good, but if the CTE beyond the T_g temperature is extremely high then the high T_g has less benefit. The temperature of a circuit during lead-free soldering is typically around 240°C to 260°C, depending on many things, but that temperature is normally well beyond the T_g of most PCB materials. If the CTE of the material

is very high when considering the range of the lead-free soldering temperatures, that can be negative for the PCB surviving soldering, even if the T_g is a high value. A well-suited material for lead-free soldering should have a minimal transition of CTE values through the T_g temperature and a relatively low CTE beyond the T_g value. Ideally, the material should have a T_g that is higher than the lead-free soldering temperature. A simple drawing representing a TMA curve for a laminate is shown in Figure 1.

The value for the CTE is also critical. For the x-y plane of the material, or the surface plane, a material with a CTE that matches copper is best; that number is about 16 ppm/°C. In the z-axis (thickness axis), the CTE of the material should be ideally around the same number. However, due to the complexities of laminate, it is usually much higher. Generally, it is believed that a z-axis CTE of about 70

ppm/°C or less is good for thermal issues and a lower number is better.

The T_d value of a laminate is sometimes not considered, but it can be a good indicator for lead-free soldering performance. If the T_d of the material is above the lead-free soldering temperature, it is sometimes assumed good for this process. In reality, the definition of T_d should be considered as well as the physics regarding this property. The T_d is defined as the temperature where the material is losing 5% of its mass or more. As the temperature is raised and approaches the T_d , some mass loss occurs that will develop stresses inside the material which can contribute to delamination.

A material with a T_d that is near the lead-free soldering temperature can be a concern because, even though it may not be losing enough mass to be defined as within the decomposition range, it could be losing enough to cause significant stress build-up. It has been shown that a material with a T_d of 300°C can have issues with lead-free soldering. However, in the same study, a material with a T_d of 400°C had no issues. To be fair, the

material with the lower T_d also had a higher CTE at the lead-free soldering temperatures, which aggravates the issue.

There are also peel strength issues at the lead-free soldering temperatures that can be important as well. Understanding the T_g , T_d and the CTE is very important for lead-free soldering issues during assembly and reworking operations. **PCB**



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What's in the Box?

by *Real Time with...APEX EXPO 2011*



Greg Bull of Rogers Corporation opens the box to reveal the New Product Innovation Award presented to Rogers for the company's RT/Duroid 6035HTC high-frequency laminate.



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